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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Adae-Amoakoh *et al.*)	Examiner: Andujar, Leonardo
)	
Serial No.: 09/827,014)	
)	Art Unit: 2826
Filed: 4/5/01)	
)	

For: **ECONOMICAL HIGH DENSITY CHIP CARRIER**   ~~FAX RECEIVED~~

Commissioner for Patents
Washington, D.C. 20231

APR 0 7 2003

TECHNOLOGY CENTER 2800

Sir:

This paper is being filed in response to a Final Office Action dated February 26, 2003 in connection with the above-identified application. Reconsideration and allowance are respectfully requested in view of the Amendments and Remarks below.

Amendment

In the Claims:

Claims 1-6, 9 and 20 have been amended prior to the present office action response. No claims are amended herein in the present office action response. Currently pending claims 1-9 and 20 for consideration by the Examiner are as follows:

1. (PREVIOUSLY AMENDED) An electronic structure comprising:

a substrate having a dielectric layer between a first metal layer and a second metal layer, the second metal layer being disposed above the first metal layer, the first metal layer having a

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CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)

Applicant(s):   Adae-Amoakoh et al.

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Serial No. 09/827,014	Filing Date 4/5/2001	Examiner Andujar, Leonardo	Group Art Unit 2826

Invention: **ECONOMICAL HIGH DENSITY CHIP CARRIER**

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I hereby certify that this _____ **Amendment (8 pages-last page Appendix A)** _____
(Identify type of correspondence)

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on _____ **4/7/2003** _____
(Date)

Kim Dwileski
(Typed or Printed Name of Person Signing Certificate)

(Signature)

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P10/REV01